

TOSHIBA Field Effect Transistor Silicon P-Channel MOS Type (Ultra-High-speed U-MOSIII)

TPCA8107-H

High Efficiency DC/DC Converter Applications

Notebook PC Applications

Portable Equipment Applications

CCFL Inverter Applications

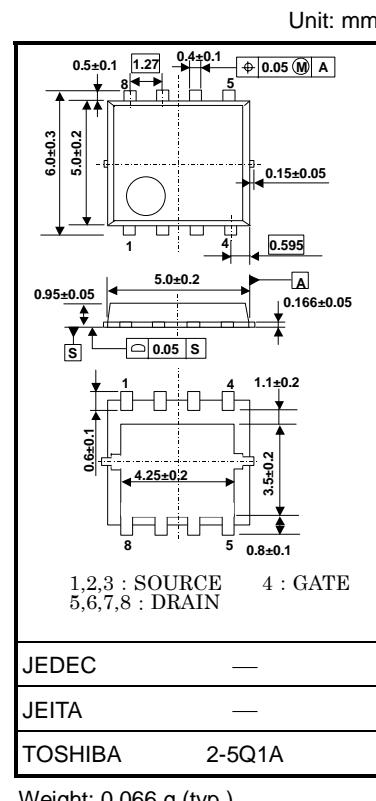
- Small footprint due to a small and thin package
- High speed switching
- Small gate charge: QSW = 9.7 nC (typ.)
- Low drain-source ON-resistance: RDS (ON) = 24mΩ (typ.)
- High forward transfer admittance: |Y_{fs}| = 14 S (typ.)
- Low leakage current: IDSS = -10 μA (max) (VDS = -40 V)
- Enhancement mode: V_{th} = -0.8 to -2.0 V (VDS = -10 V, ID = -1 mA)

Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Drain-source voltage	V _{DSS}	-40	V
Drain-gate voltage (R _{GS} = 20 kΩ)	V _{DGR}	-40	V
Gate-source voltage	V _{GSS}	±20	V
Drain current	DC (Note 1)	I _D	A
	Pulsed (Note 1)	I _{DP}	A
Drain power dissipation (Tc=25°C)	P _D	30	W
Drain power dissipation (t = 10 s) (Note 2a)	P _D	2.8	W
Drain power dissipation (t = 10 s) (Note 2b)	P _D	1.6	W
Single-pulse avalanche energy (Note 3)	E _{AS}	26	mJ
Avalanche current	I _{AR}	-7.5	A
Repetitive avalanche energy (Note 2a) (Note 4)	E _{AR}	1.9	mJ
Channel temperature	T _{ch}	150	°C
Storage temperature range	T _{stg}	-55 to 150	°C

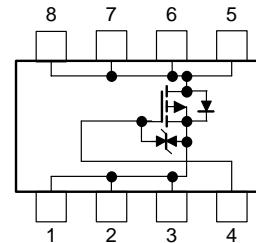
Note: For Notes 1 to 4, refer to the next page.

This transistor is an electrostatic-sensitive device. Handle with care.



Weight: 0.066 g (typ.)

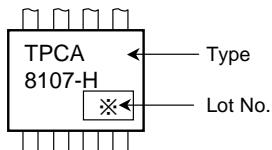
Circuit Configuration



Thermal Characteristics

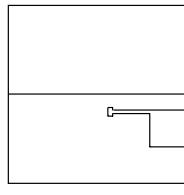
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case ($T_c=25^\circ\text{C}$)	$R_{th}(\text{ch-c})$	4.17	$^\circ\text{C}/\text{W}$
Thermal resistance, channel to ambient ($t = 10 \text{ s}$) (Note 2a)	$R_{th}(\text{ch-a})$	44.6	$^\circ\text{C}/\text{W}$
Thermal resistance, channel to ambient ($t = 10 \text{ s}$) (Note 2b)	$R_{th}(\text{ch-a})$	78.1	$^\circ\text{C}/\text{W}$

Marking (Note 5)



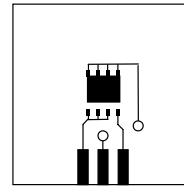
Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



(a)

FR-4
 $25.4 \times 25.4 \times 0.8$
(Unit: mm)



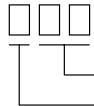
(b)

FR-4
 $25.4 \times 25.4 \times 0.8$
(Unit: mm)

Note 3: $V_{DD} = -24 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 0.5 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = -7.5 \text{ A}$

Note 4: Repetitive rating: pulse width limited by max channel temperature

Note 5: * Weekly code: (Three digits)



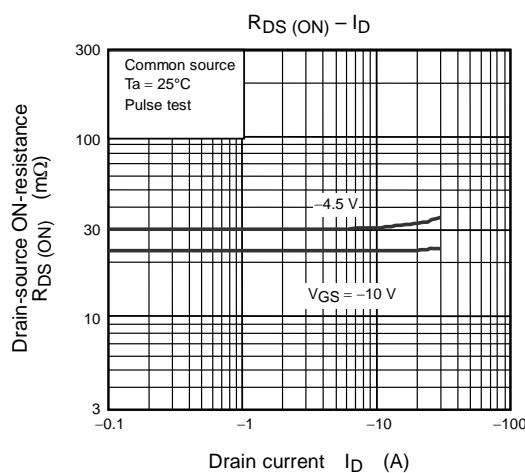
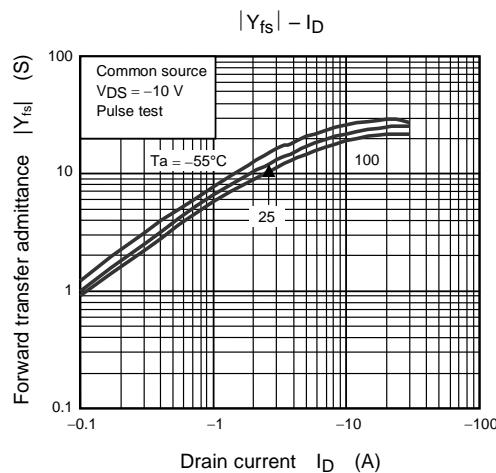
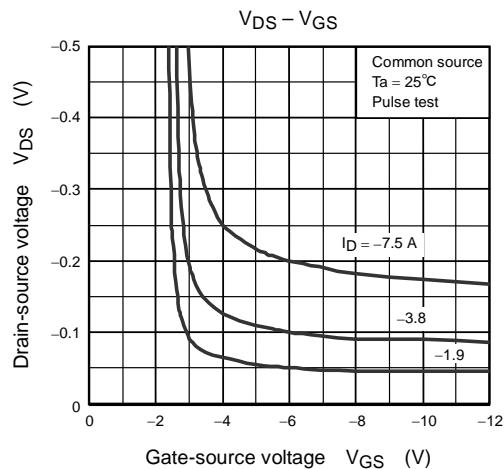
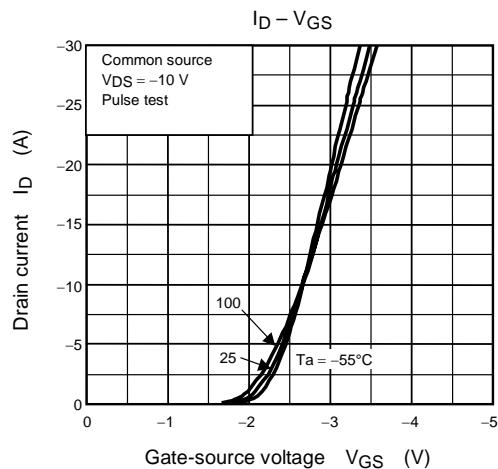
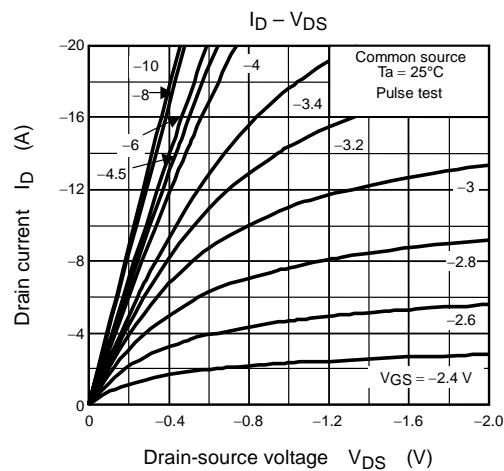
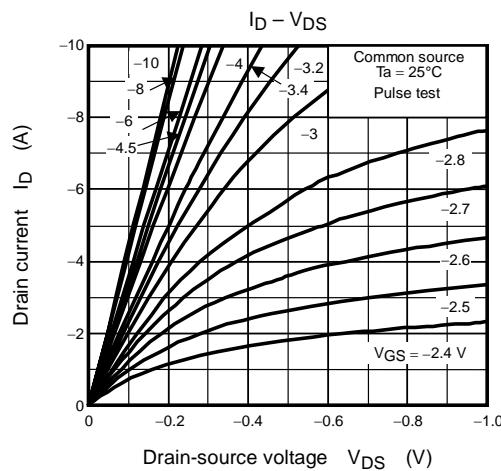
Week of manufacture
(01 for first week of year, continuing up to 52 or 53)
Year of manufacture
(The last digit of the calendar year)

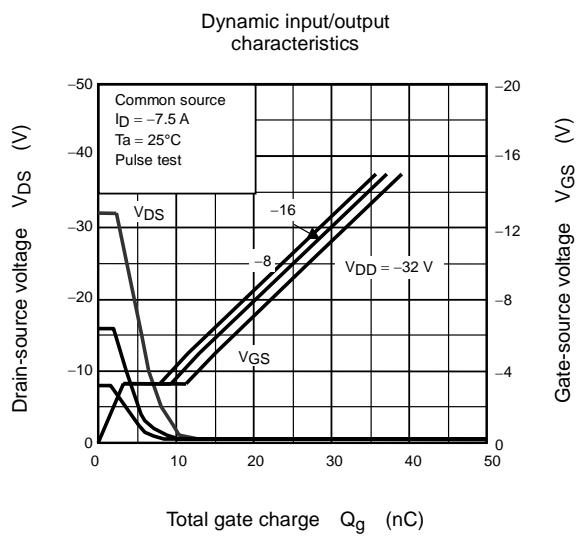
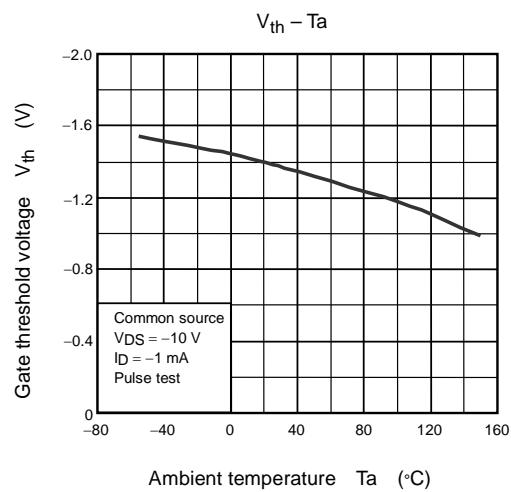
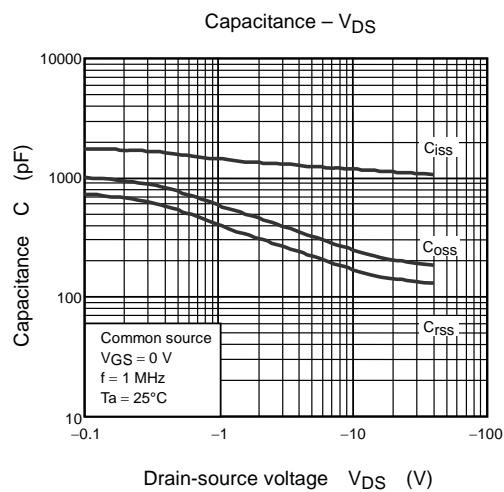
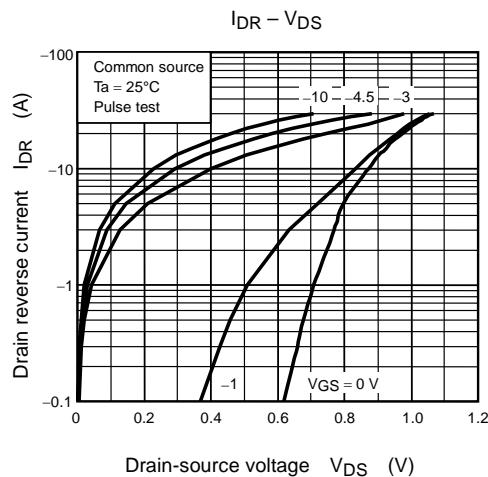
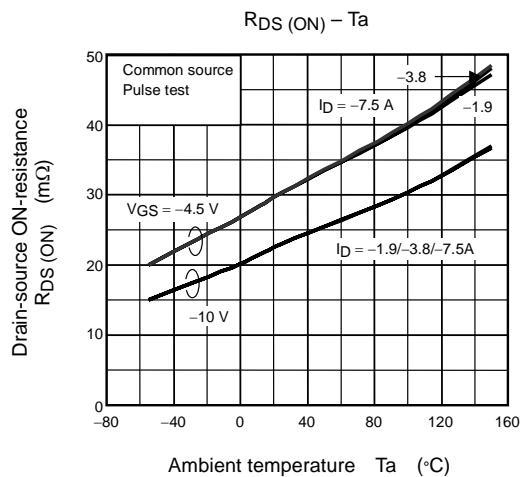
Electrical Characteristics ($T_a = 25^\circ\text{C}$)

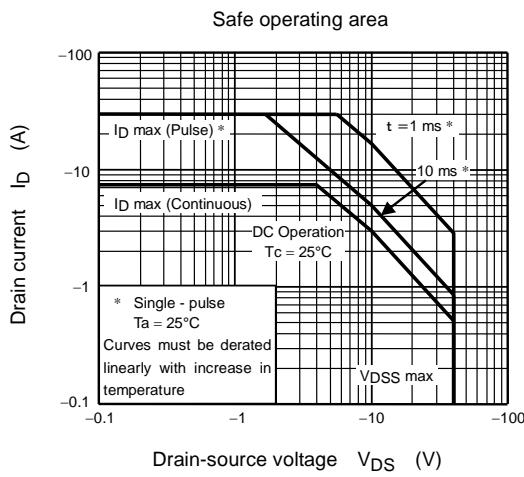
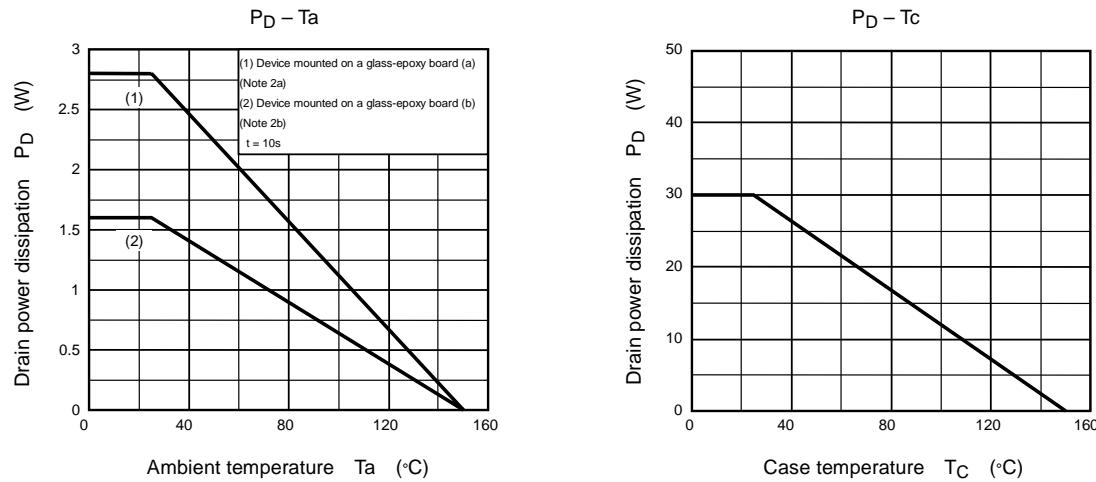
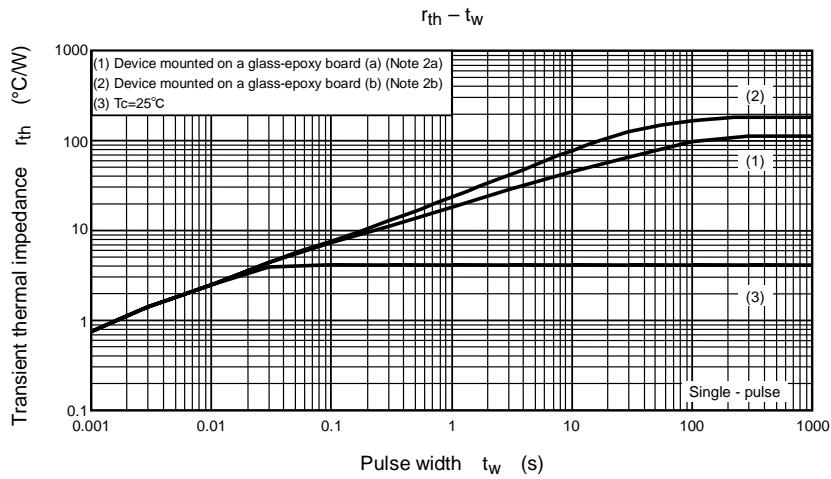
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Drain cutoff current	I_{DSS}	$V_{DS} = -40\text{ V}, V_{GS} = 0\text{ V}$	—	—	-10	μA
Drain-source breakdown voltage	$V_{(\text{BR})\text{ DSS}}$	$I_D = -10\text{ mA}, V_{GS} = 0\text{ V}$	-40	—	—	V
	$V_{(\text{BR})\text{ DSX}}$	$I_D = -10\text{ mA}, V_{GS} = 20\text{ V}$	-20	—	—	
Gate threshold voltage	V_{th}	$V_{DS} = -10\text{ V}, I_D = -1\text{ mA}$	-0.8	—	-2.0	V
Drain-source ON-resistance	$R_{DS\text{ (ON)}}$	$V_{GS} = -4.5\text{ V}, I_D = -3.8\text{ A}$	—	29	37	$\text{m}\Omega$
		$V_{GS} = -10\text{ V}, I_D = -3.8\text{ A}$	—	24	30	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -10\text{ V}, I_D = -3.8\text{ A}$	7	14	—	S
Input capacitance	C_{iss}	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	1190	—	pF
Reverse transfer capacitance	C_{rss}		—	170	—	
Output capacitance	C_{oss}		—	250	—	
Switching time	Rise time	t_r	 $V_{DD} \approx -20\text{ V}$ Duty $\leq 1\%$, $t_w = 10\text{ }\mu\text{s}$	—	5	ns
	Turn-on time	t_{on}		—	12	
	Fall time	t_f		—	12	
	Turn-off time	t_{off}		—	43	
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx -32\text{ V}, V_{GS} = -10\text{ V}$	$I_D = -7.5\text{ A}$	—	27	nC
		$V_{DD} \approx -32\text{ V}, V_{GS} = -5\text{ V}$	$I_D = -7.5\text{ A}$	—	15	
Gate-source charge 1	Q_{gs1}	$V_{DD} \approx -32\text{ V}, V_{GS} = -10\text{ V}$	$I_D = -7.5\text{ A}$	—	3.2	nC
Gate-drain ("Miller") charge	Q_{gd}		—	8.1		
Gate switch charge	Q_{SW}		—	9.7		

Source-Drain Ratings and Characteristics ($T_a = 25^\circ\text{C}$)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Drain reverse current	I_{DRP}	—	—	—	-30	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = -7.5\text{ A}, V_{GS} = 0\text{ V}$	—	—	1.2	V







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